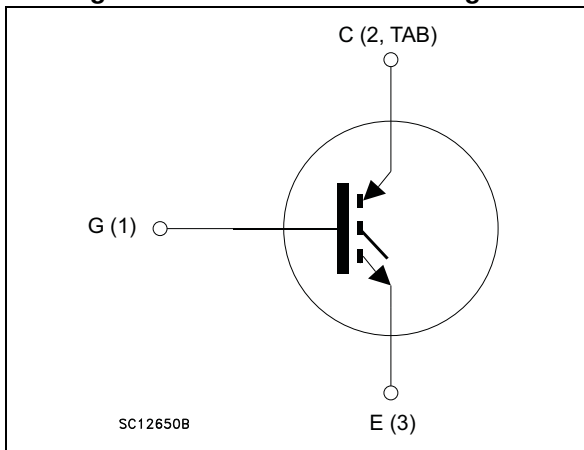


Figure 1. Internal schematic diagram



### Features

- Maximum junction temperature:  $T_J = 175\text{ }^\circ\text{C}$
- Very high speed switching series
- Tail-less switching off
- Low saturation voltage:  $V_{CE(sat)} = 1.8\text{ V (typ.)}$   
@  $I_C = 20\text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance
- Lead free package

### Applications

- Photovoltaic inverters
- Uninterruptible power supply
- Welding
- Power factor correction
- Very high frequency converters

### Description

This device is an IGBT developed using an advanced proprietary trench gate and field stop structure. The device is part of the "V" series of IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, a positive  $V_{CE(sat)}$  temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1. Device summary

Order code	Marking	Package	Packaging
STGB20V60F	GB20V60F	D <sup>2</sup> PAK	Tape and reel
STGP20V60F	GP20V60F	TO-220	Tube

## Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ )	600	V
$I_C$	Continuous collector current at $T_C = 25\text{ °C}$	40	A
$I_C$	Continuous collector current at $T_C = 100\text{ °C}$	20	A
$I_{CP}^{(1)}$	Pulsed collector current	80	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$P_{TOT}$	Total dissipation at $T_C = 25\text{ °C}$	167	W
$T_{STG}$	Storage temperature range	- 55 to 150	$^{\circ}\text{C}$
$T_J$	Operating junction temperature	- 55 to 175	$^{\circ}\text{C}$

1. Pulse width limited by maximum junction temperature.

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance junction-case	0.9	$^{\circ}\text{C/W}$
$R_{thJA}$	Thermal resistance junction-ambient	50	$^{\circ}\text{C/W}$

## 2 Electrical characteristics

$T_J = 25\text{ °C}$  unless otherwise specified.

**Table 4. Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage ( $V_{GE} = 0$ )	$I_C = 2\text{ mA}$	600			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 20\text{ A}$		1.8	2.2	V
		$V_{GE} = 15\text{ V}, I_C = 20\text{ A}$ $T_J = 125\text{ °C}$		2.15		
		$V_{GE} = 15\text{ V}, I_C = 20\text{ A}$ $T_J = 175\text{ °C}$		2.3		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1\text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current ( $V_{GE} = 0$ )	$V_{CE} = 600\text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20\text{ V}$			250	nA

**Table 5. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}, f = 1\text{ MHz},$ $V_{GE} = 0$	-	2800	-	pF
$C_{oes}$	Output capacitance		-	110	-	pF
$C_{res}$	Reverse transfer capacitance		-	64	-	pF
$Q_g$	Total gate charge	$V_{CC} = 480\text{ V}, I_C = 20\text{ A},$ $V_{GE} = 15\text{ V},$ see <a href="#">Figure 22</a>	-	116	-	nC
$Q_{ge}$	Gate-emitter charge		-	24	-	nC
$Q_{gc}$	Gate-collector charge		-	50	-	nC

Table 6. Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 20\text{ A}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 100\text{ A}/\mu\text{s}$ see <a href="#">Figure 21</a>	-	38	-	ns
$t_r$	Current rise time		-	10	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1556	-	$\text{A}/\mu\text{s}$
$t_{d(off)}$	Turn-off delay time		-	149	-	ns
$t_f$	Current fall time		-	15	-	ns
$E_{on}^{(1)}$	Turn-on switching losses		-	200	-	$\mu\text{J}$
$E_{off}^{(2)}$	Turn-off switching losses		-	130	-	$\mu\text{J}$
$E_{ts}$	Total switching losses	-	330	-	$\mu\text{J}$	
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 20\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{GE} = 15\text{ V}$ , $T_J = 175\text{ }^\circ\text{C}$ , see <a href="#">Figure 21</a>	-	37	-	ns
$t_r$	Current rise time		-	12	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1340	-	$\text{A}/\mu\text{s}$
$t_{d(off)}$	Turn-off delay time		-	150	-	ns
$t_f$	Current fall time		-	23	-	ns
$E_{on}^{(1)}$	Turn-on switching losses		-	430	-	$\mu\text{J}$
$E_{off}^{(2)}$	Turn-off switching losses		-	210	-	$\mu\text{J}$
$E_{ts}$	Total switching losses	-	640	-	$\mu\text{J}$	

1. Energy losses include reverse recovery of the external diode. The diode is the same of the copacked STGW20V60DF
2. Turn-off losses include also the tail of the collector current.

## 2.1 Electrical characteristics (curves)

Figure 2. Power dissipation vs. case temperature

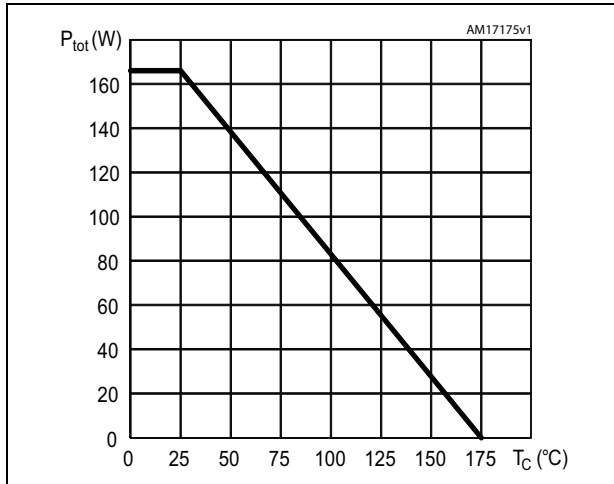


Figure 3. Collector current vs. case temperature

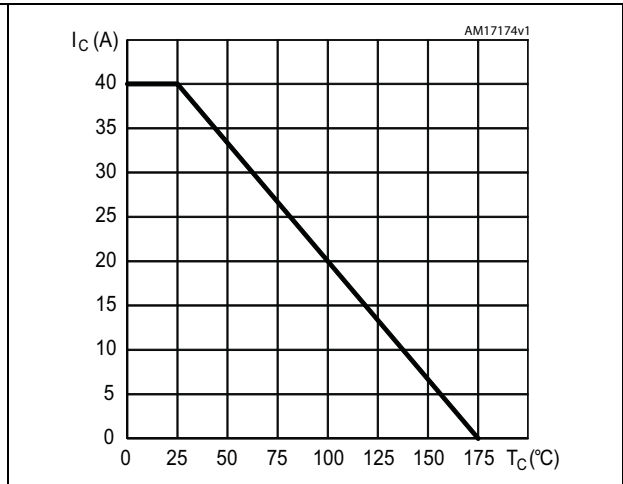


Figure 4. Output characteristics ( $T_J = 25^\circ\text{C}$ )

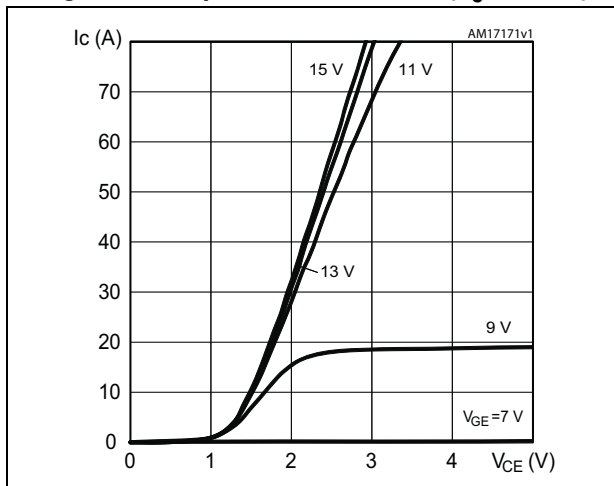


Figure 5. Output characteristics ( $T_J = 175^\circ\text{C}$ )

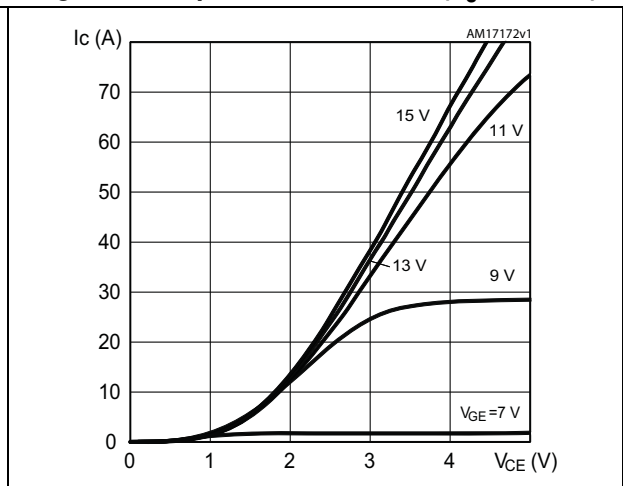


Figure 6.  $V_{CE(SAT)}$  vs. junction temperature

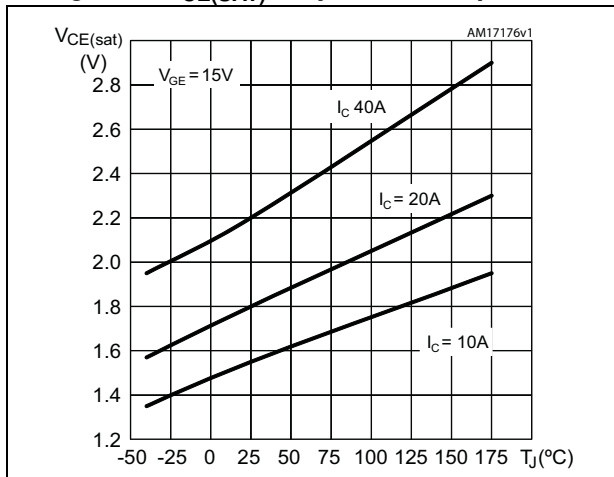


Figure 7.  $V_{CE(SAT)}$  vs. collector current

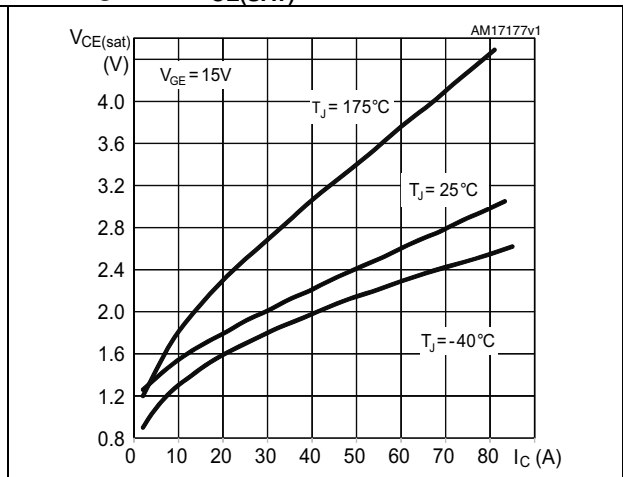


Figure 8. Safe operating area

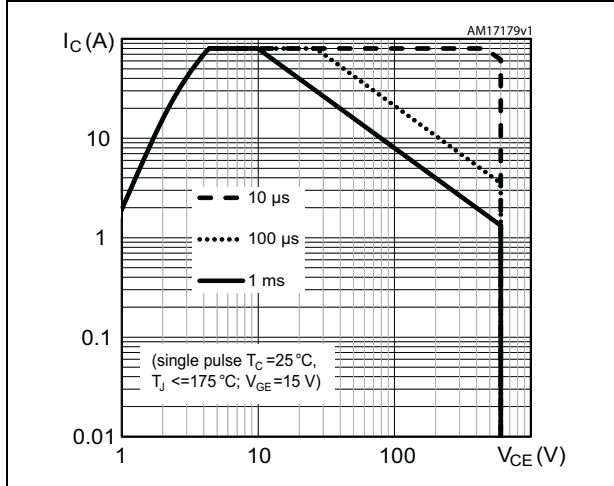


Figure 9. Transfer characteristics

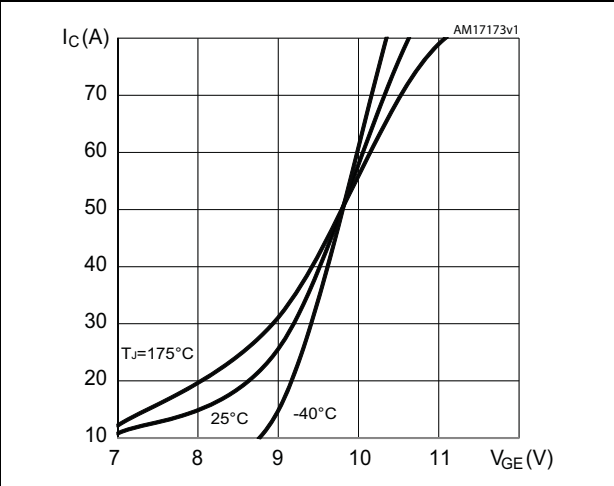


Figure 10. Normalized  $V_{GE(th)}$  vs. junction temperature

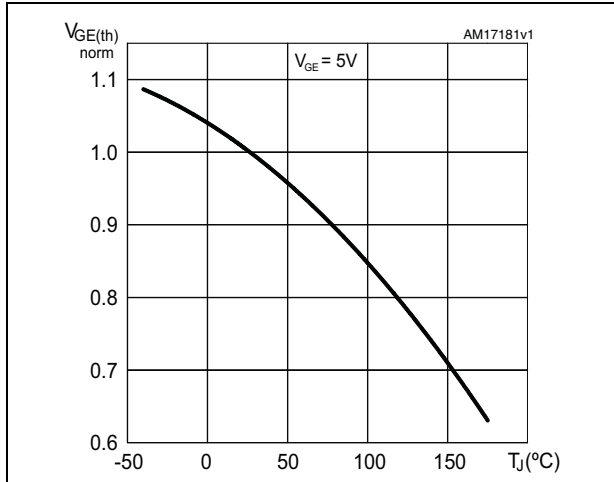


Figure 11. Normalized  $V_{(BR)CES}$  vs. junction temperature

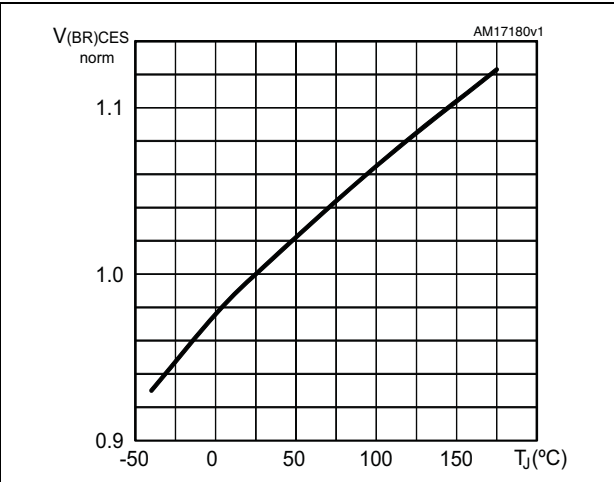


Figure 12. Capacitance variations

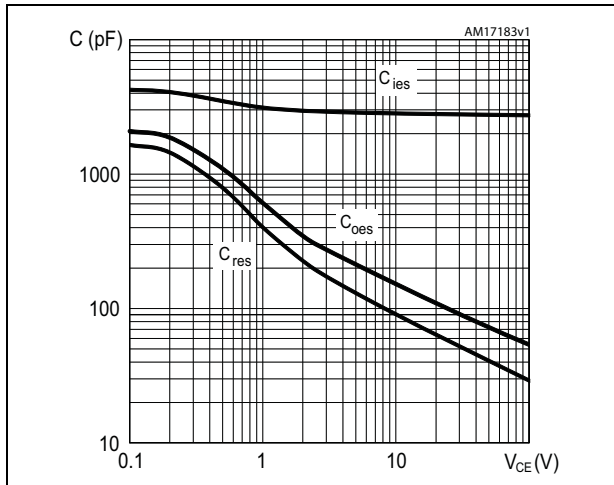


Figure 13. Gate charge vs. gate-emitter voltage

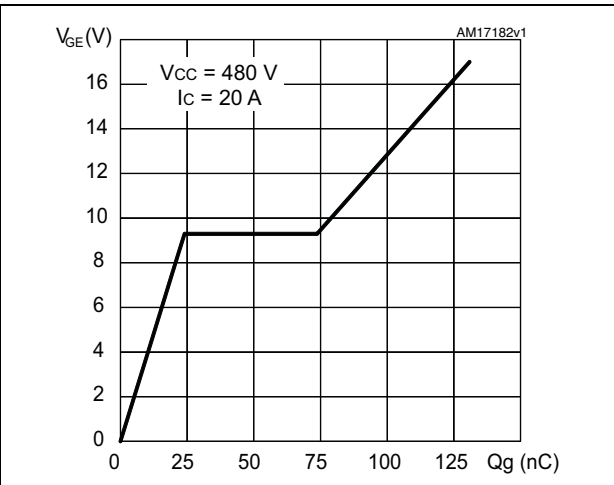


Figure 14. Switching losses vs. collector current

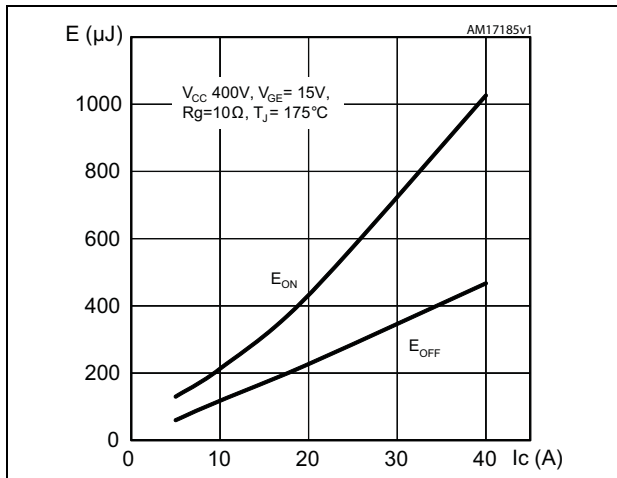


Figure 15. Switching losses vs. gate resistance

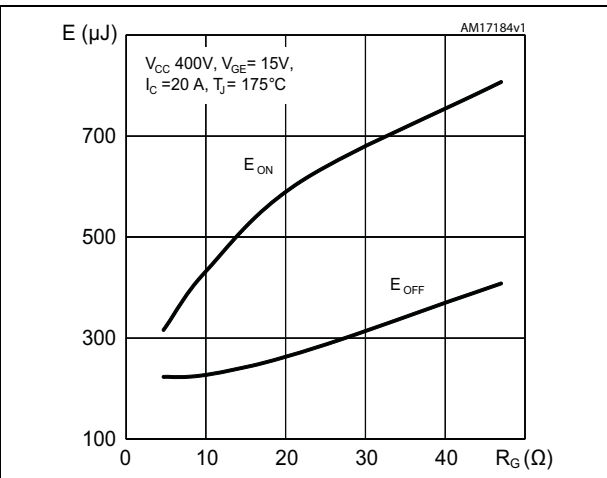


Figure 16. Switching losses vs. junction temperature

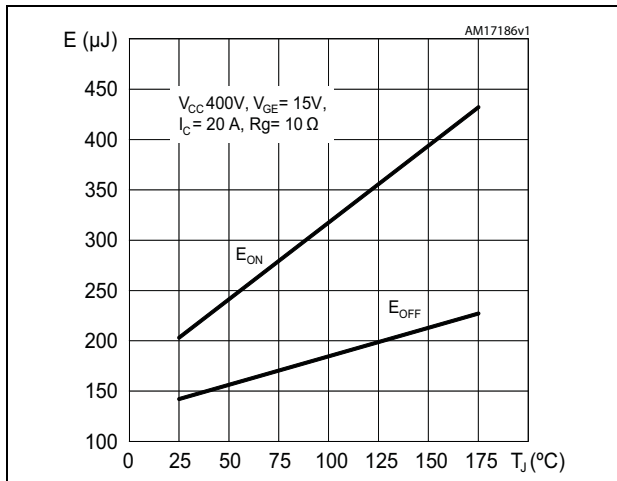


Figure 17. Switching losses vs. collector emitter voltage

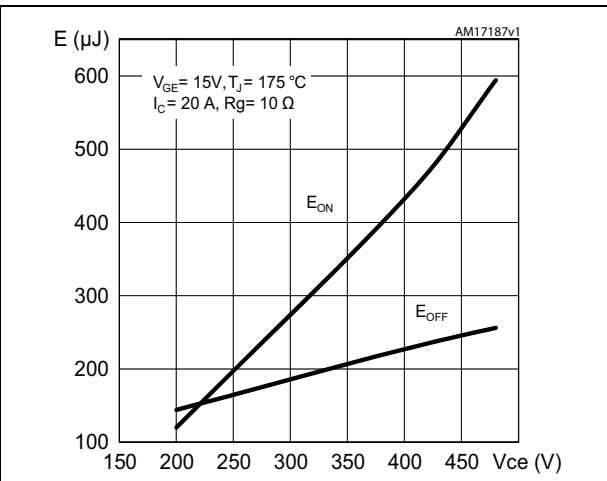


Figure 18. Switching times vs. collector current

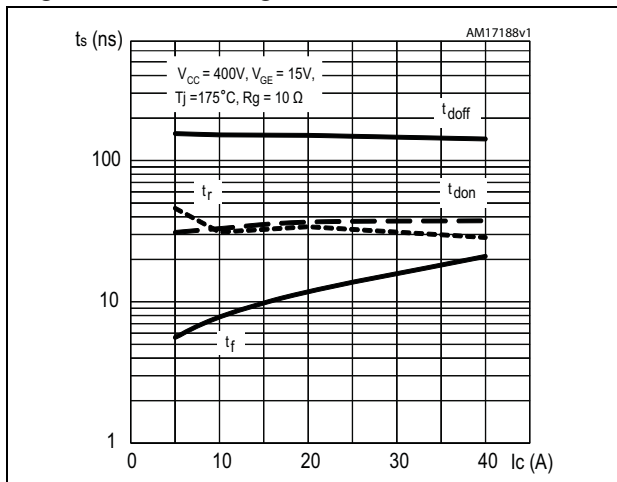


Figure 19. Switching times vs. gate resistance

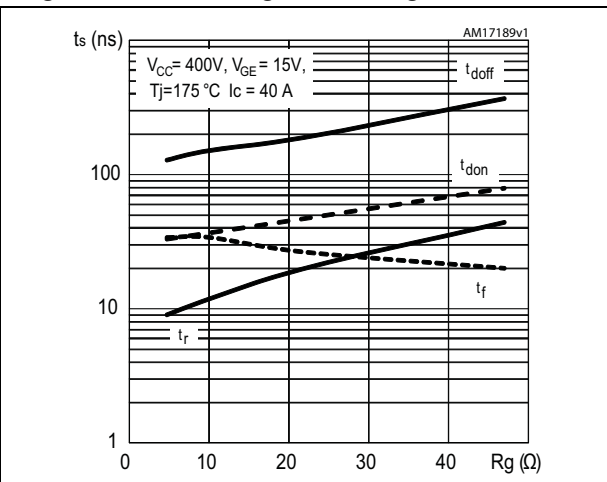
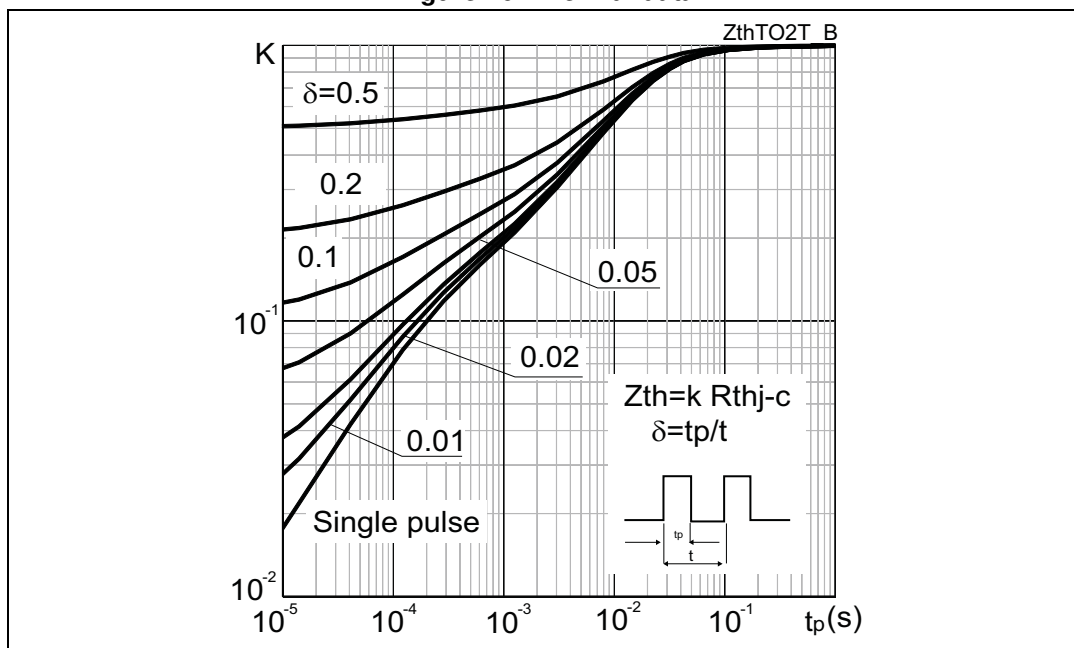




Figure 20. Thermal data





## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Table 7. D<sup>2</sup>PAK (TO-263) mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
E	10		10.40
E1	8.50		
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 24. D<sup>2</sup>PAK (TO-263) drawing

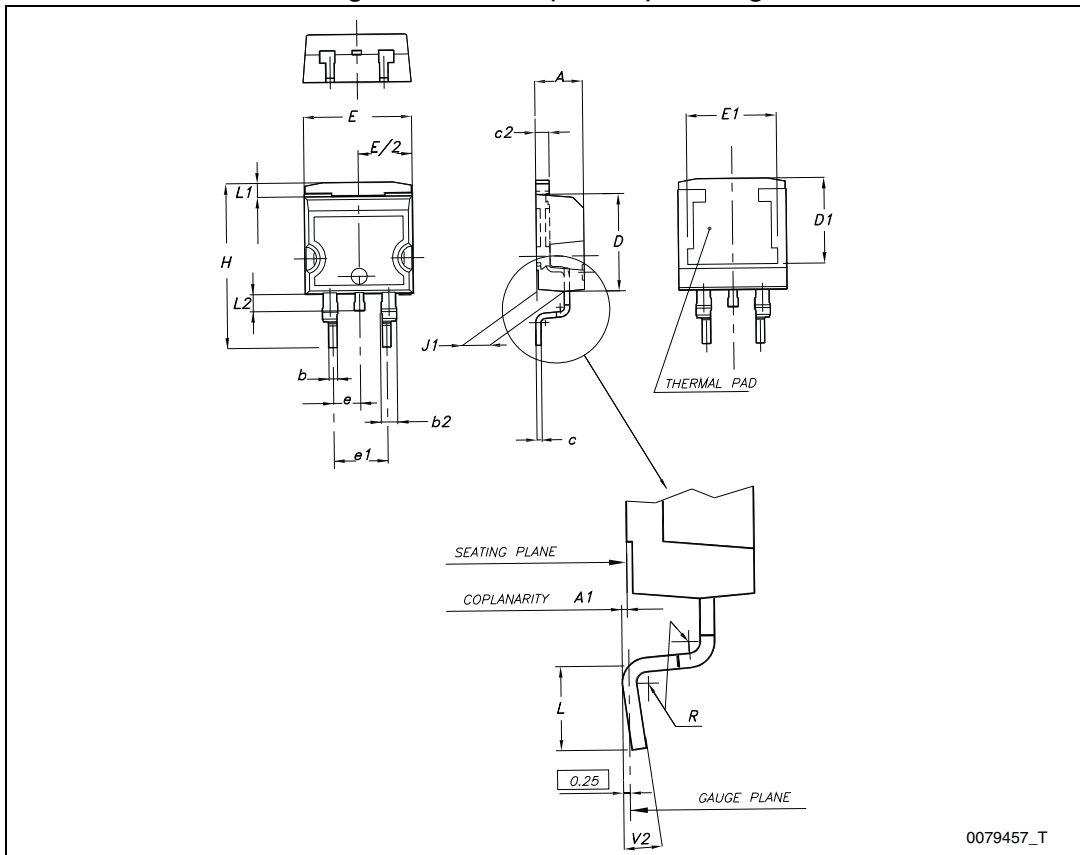
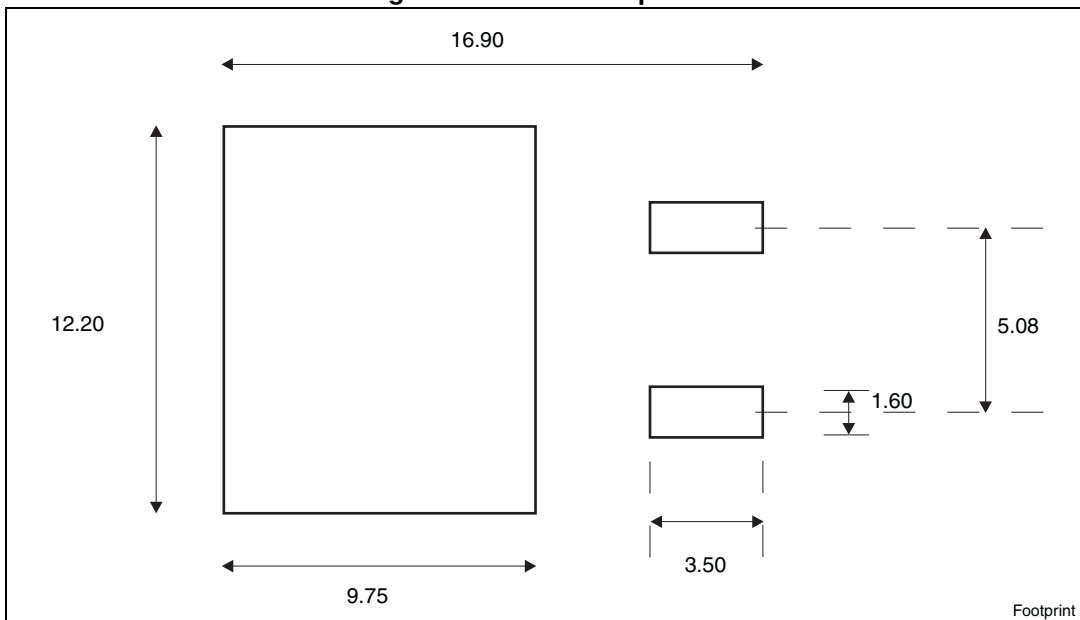


Figure 25. D<sup>2</sup>PAK footprint<sup>(a)</sup>

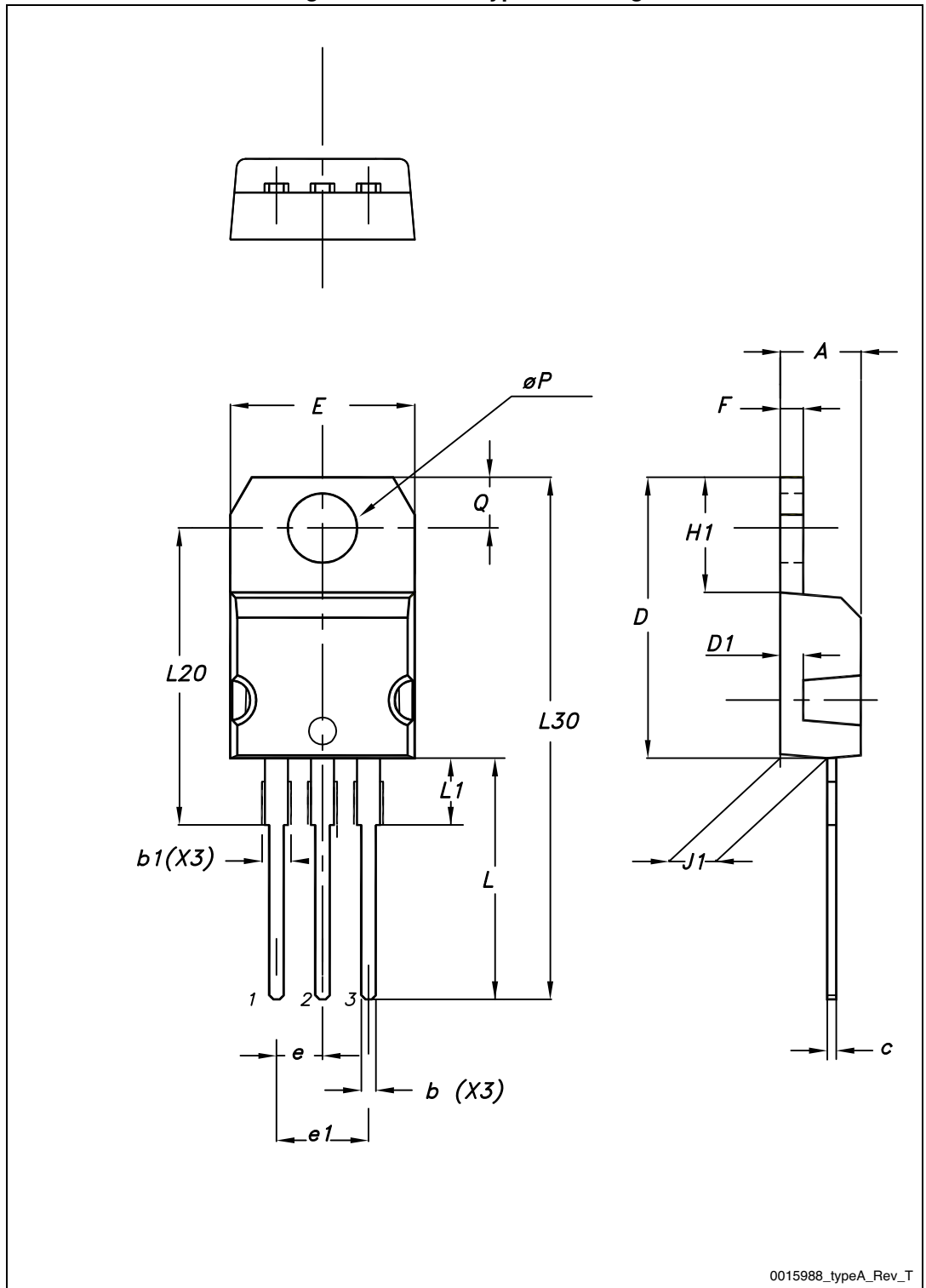


a. All dimension are in millimeters

Table 8. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 26. TO-220 type A drawing



0015988\_typeA\_Rev\_T

## 5 Packaging mechanical data

Table 9. D<sup>2</sup>PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Figure 27. Tape

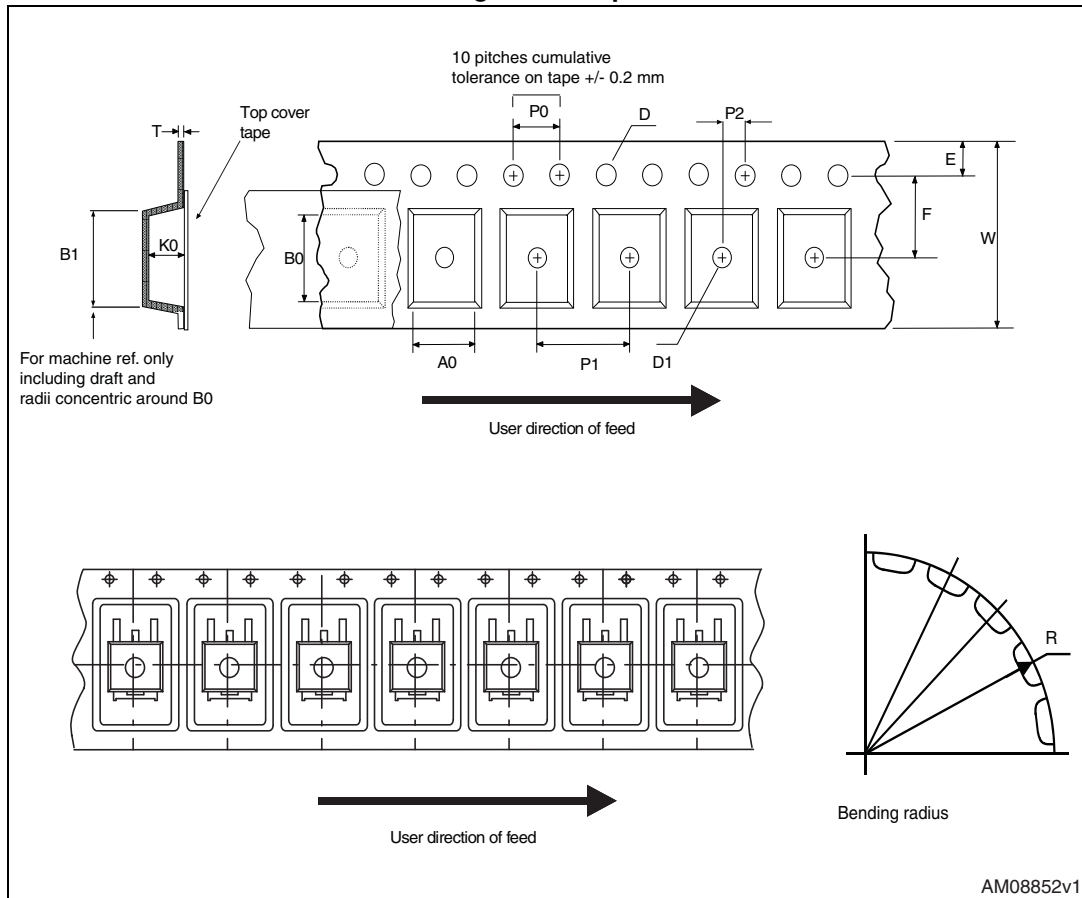
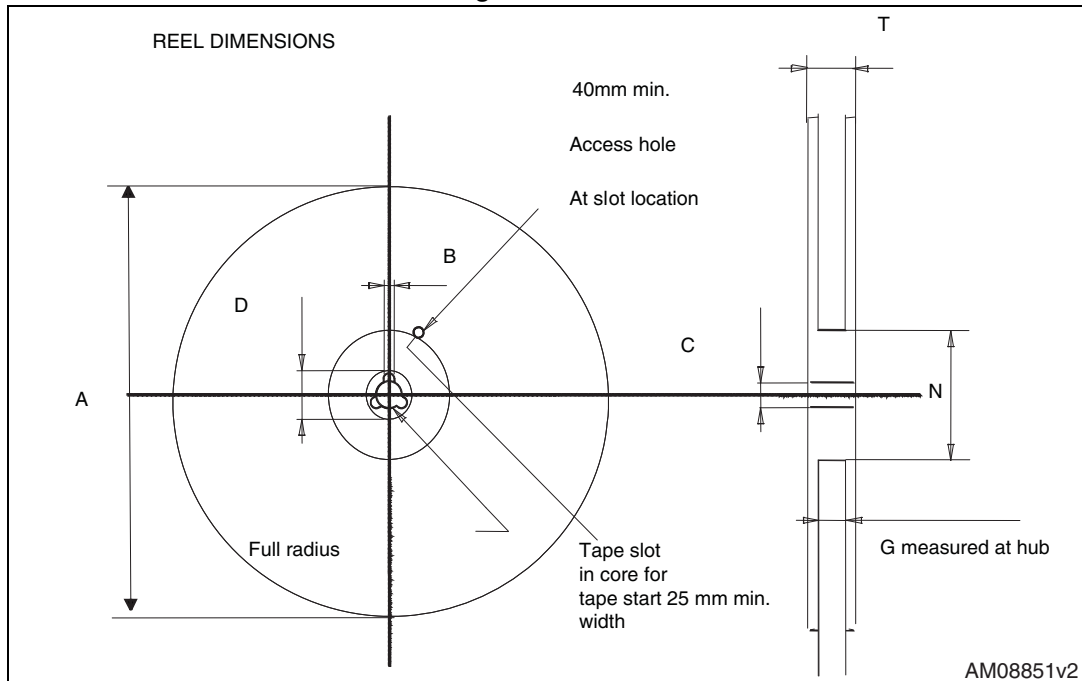


Figure 28. Reel





## 6 Revision history

Table 10. Document revision history

Date	Revision	Changes
11-Jul-2013	1	Initial release.

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